

## Product End-of-Life Disassembly Instructions

Product Category: **Storage**

### Marketing Name / Model

HPE MSA 2070 Storage

HPE MSA 2072 Storage

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE). Detailed removal instructions are available in the server Maintenance and Service Guide on the [HPE Product Support Center](#).

### 1.0 Items Requiring Selective Treatment

1.1 The items listed below are classified as requiring selective treatment.

1.2 Quantities vary by product configuration

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm 2 in each of 2 I/O modules, 1 in each of 2 power cooling modules 1 on the chassis midplane	7
Batteries	All types including standard alkaline and lithium coin or button style batteries. 1 coin battery in each of 2 I/O modules	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Quantity varies by product configuration and power supply model selected 1 capacitor in each of 2 power supplies 1 supercapacitor in each of 2 I/O modules	4
External electrical cables and cords	Quantity depends on number of power supplies, networking devices, and I/O devices 1 power cord for each 2 Power supplies 2 sas expansion cables per storage system	4

Item Description	Notes	Quantity of items included in product
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx drives	T10, T15
Phillips driver	#0, #1, #2
Pliers	small
Drill	standard

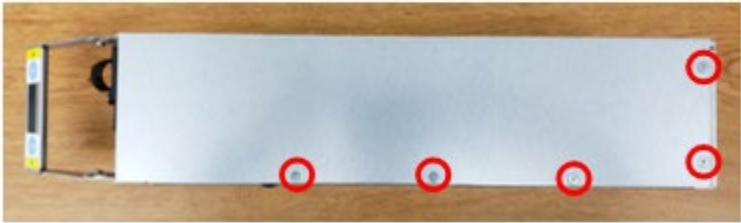
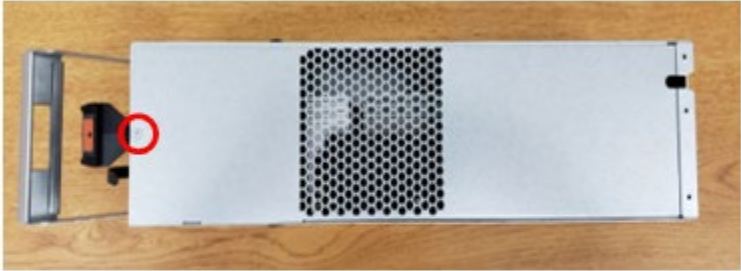
## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment. Provide links to the product Maintenance and Service Guide where reference is needed for detailed disassembly instructions.

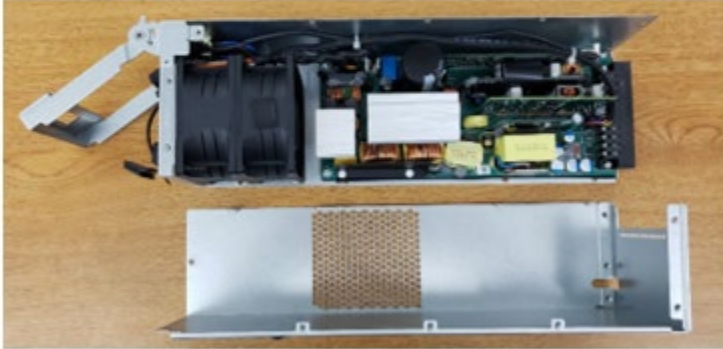
1. Remove the bezel and hubcaps from the front of the enclosure.
2. Remove all disk drives.
3. For each disk drive, remove the disk from the plastic sled.
4. Remove both power cooling modules (PCMs).
5. Remove both I/O modules (IOMs).
6. Disassemble each PCM. See PCM disassembly.
7. Disassemble each IOM. See IOM disassembly.
8. Disassemble the chassis. See Chassis disassembly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

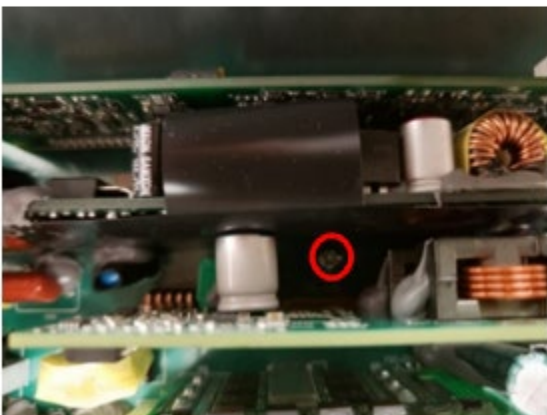
Attachment 1 Remove the casing screws.



Attachment 2 Separate the casing.



Attachment 3 Remove the five PCA mounting screws.



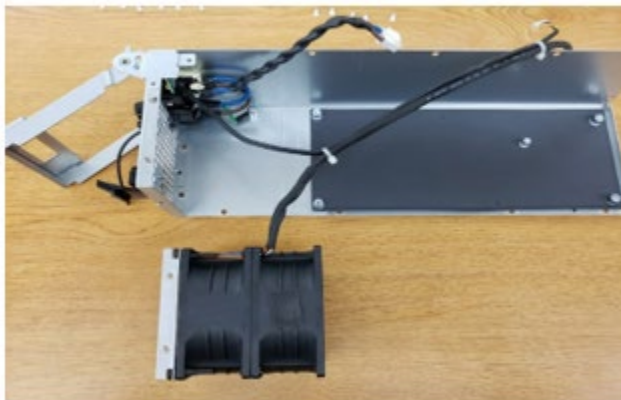
Attachment 4 Remove the cabling connectors.



Attachment 5 Remove the PCA from the casing.



Attachment 6 Remove the fans from the casing.



**I/O module disassemble procedure**

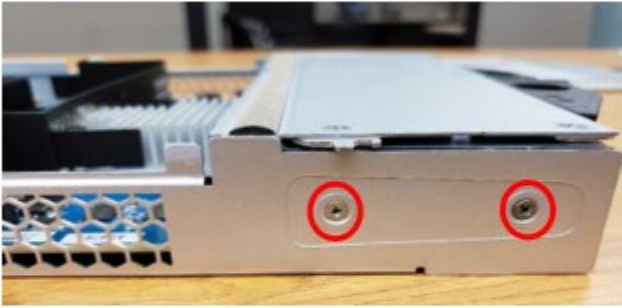
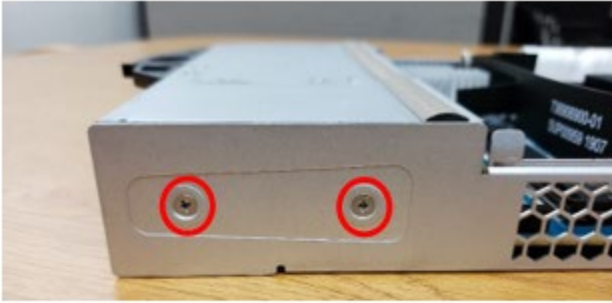
Attachment 1 Remove the two screws from the lid.



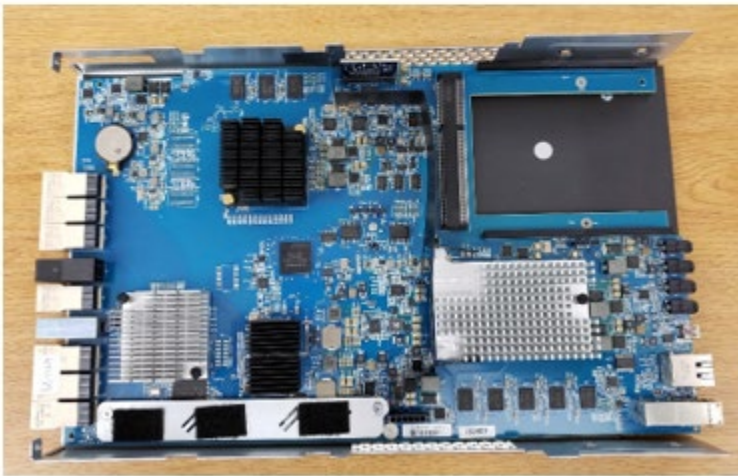
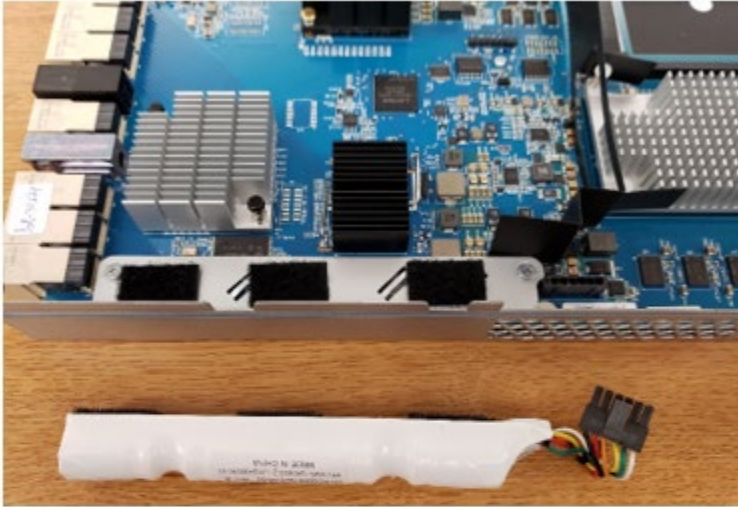
Attachment 2 Remove the host module by removing the two screws and pulling it out.



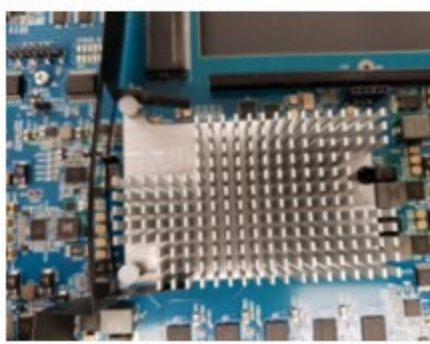
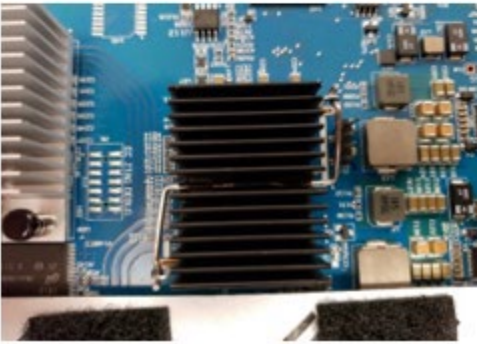
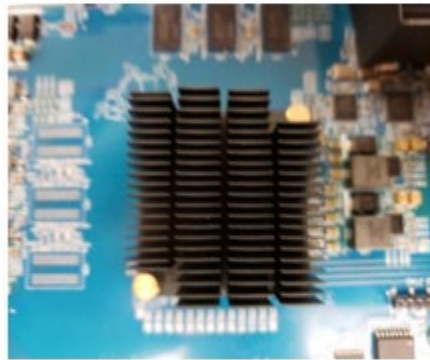
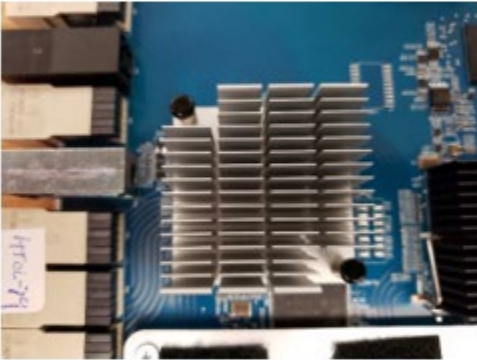
Attachment 3 Remove the faceplate by removing the seven screws



Attachment 4 Remove the supercapacitor pack.



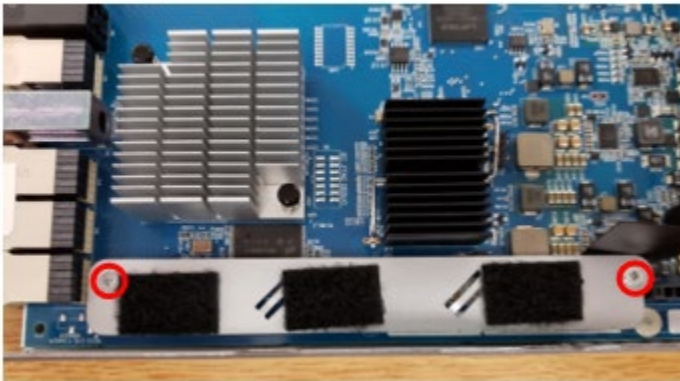
Attachment 5 Remove the four heatsinks by removing the pushpins. To remove the pushpins, compress the pushpin and use pliers to squeeze and pull out the other end.



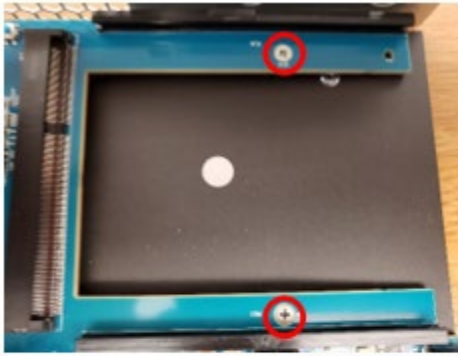
Attachment 6 Remove the coin battery.



Attachment 7 Remove the supercapacitor mounting plate (if present).

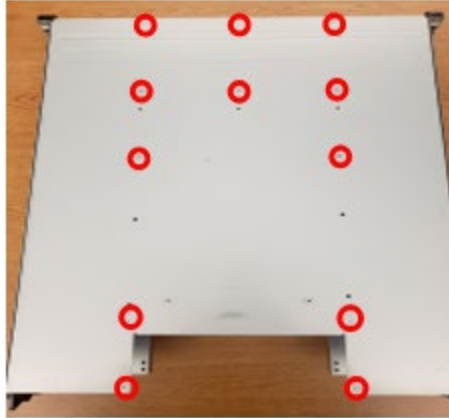


Attachment 8 Remove the five PCA screws.

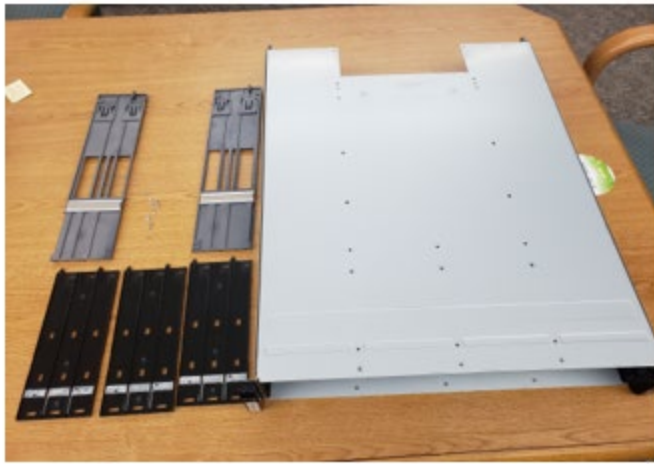


**Chassis disassembly procedure**

Attachment 1 Remove the retaining screws.



Attachment 2 Remove the plastic partitions.



Attachment 3 Remove the four screws that hold the midplane (not shown).



Attachment 4 Detach the hubcaps by removing the hubcap screws.

